

STARPOWER

SEMICONDUCTOR

IGBT

GD400SGL120C2S

Molding Type Module

1200V/400A 1 in one-package

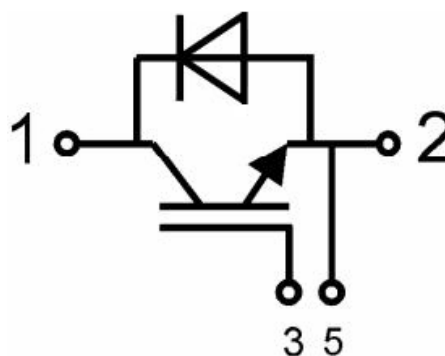


General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. It's designed for the applications such as Inverters and UPS.

Features

- High short circuit capability, self limiting to $6 \cdot I_C$
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

**Equivalent Circuit Schematic**

Typical Applications

- AC inverter drives
- Switching mode power supplies
- Electronic welders at f_{sw} up to 20kHz

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Description	GD400SGL120C2S	Units
V_{CES}	Collector-Emitter Voltage	1200	V

Symbol	Description	GD400SGL120C2S	Units
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^\circ\text{C}$ @ $T_C=100^\circ\text{C}$	650	A
		400	
$I_{CM(1)}$	Pulsed Collector Current	800	A
I_F	Diode Continuous Forward Current	400	A
I_{FM}	Diode Maximum Forward Current	800	A
P_D	Maximum power Dissipation @ $T_j=175^\circ\text{C}$	3000	W
T_{SC}	Short Circuit Withstand Time @ $T_j=125^\circ\text{C}$	10	μs
T_{jmax}	Maximum Junction Temperature	175	$^\circ\text{C}$
T_j	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^\circ\text{C}$
I^2t -value, Diode	$V_R=0\text{V}$, $t=10\text{ms}$, $T_j=125^\circ\text{C}$	27500	A^2s
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V
Mounting Torque	Power Terminal Screw:M6	2.5 to 5	N.m
	Mounting Screw:M6	3 to 6	N.m

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT $T_C=25^\circ\text{C}$ unless otherwise noted**Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{CES}	Collector-Emitter Breakdown Voltage	$T_j=25^\circ\text{C}$	1200			V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}$, $V_{GE}=0\text{V}$, $T_j=25^\circ\text{C}$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}$, $V_{CE}=0\text{V}$, $T_j=25^\circ\text{C}$			400	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=8\text{mA}$, $V_{CE}=V_{GE}$, $T_j=25^\circ\text{C}$	5.0	6.2	7.0	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=400\text{A}$, $V_{GE}=15\text{V}$, $T_j=25^\circ\text{C}$		1.9		V
		$I_C=400\text{A}$, $V_{GE}=15\text{V}$, $T_j=125^\circ\text{C}$		2.1		

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}$, $I_C=400\text{A}$, $R_G=4\Omega$, $V_{GE}=\pm 15\text{V}$,		100		ns
t_r	Rise Time			60		ns

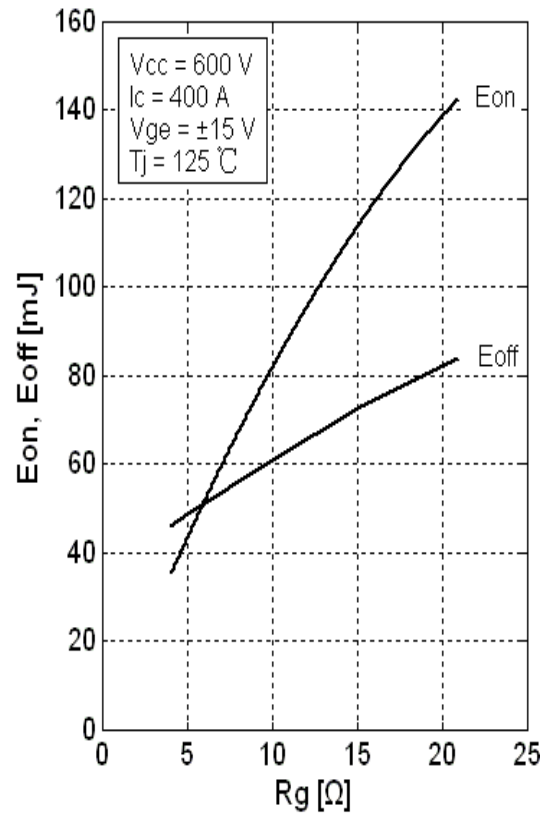
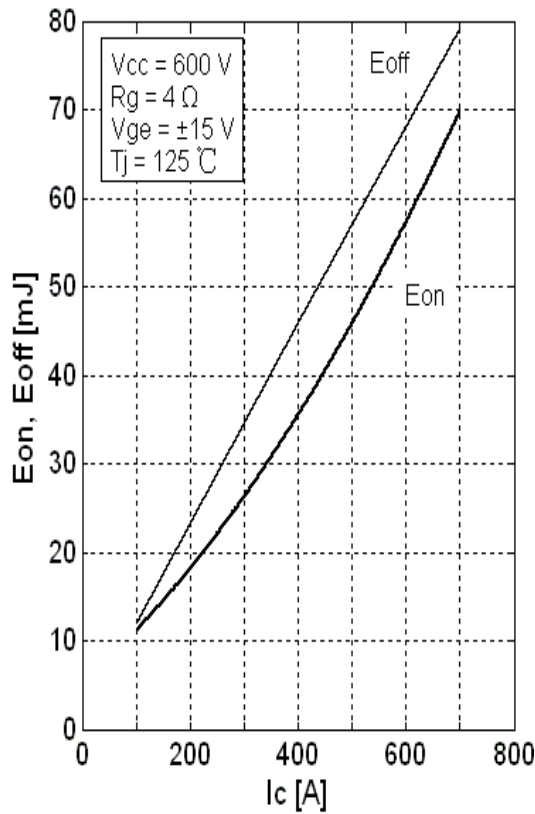
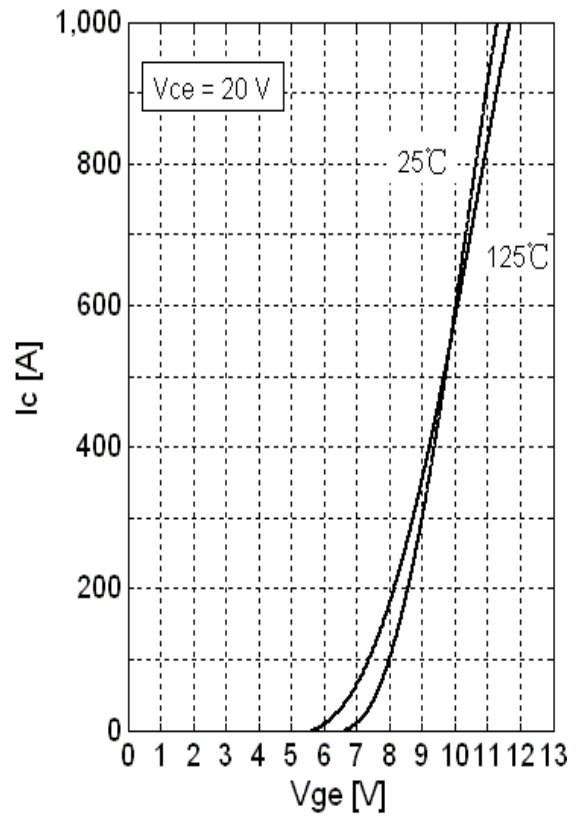
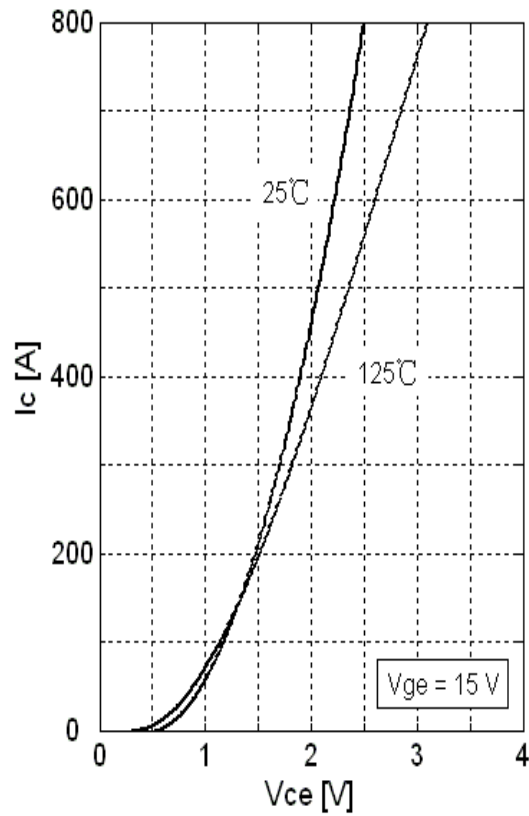
$t_{d(off)}$	Turn-Off Delay Time	$T_j=25^\circ\text{C}$		420		ns
t_f	Fall Time	$V_{CC}=600\text{V}, I_C=400\text{A},$ $R_G=4\Omega, V_{GE} = \pm 15\text{V},$ $T_j=25^\circ\text{C}$		60		ns
E_{on}	Turn-On Switching Loss			33		mJ
E_{off}	Turn-Off Switching Loss			42		mJ
$t_{d(on)}$	Turn-On Delay Time		$V_{CC}=600\text{V}, I_C=400\text{A},$ $R_G=4\Omega, V_{GE} = \pm 15\text{V},$ $T_j=125^\circ\text{C}$		120	
t_r	Rise Time			60		ns
$t_{d(off)}$	Turn-Off Delay Time			490		ns
t_f	Fall Time			75		ns
E_{on}	Turn-On Switching Loss			35		mJ
E_{off}	Turn-Off Switching Loss			46		mJ
C_{ies}	Input Capacitance	$V_{CE} = 25\text{V}, f=1\text{MHz},$ $V_{GE} = 0\text{V}$		30		nF
C_{oes}	Output Capacitance			4		nF
C_{res}	Reverse Transfer Capacitance			3		nF
I_{SC}	SC Data	$t_{sc} \leq 10\mu\text{s}, V_{GE}=15\text{V},$ $T_j=125^\circ\text{C}, V_{CC}=900\text{V},$ $V_{CEM} \leq 1200\text{V}$		1900		A
R_{Gint}	Internal Gate Resistance			0.5		Ω
L_{CE}	Stray inductance				20	nH
$R_{CC'+EE'}$	Module lead resistance, terminal to chip	$T_C=25^\circ\text{C}$		0.18		m Ω

Electrical Characteristics of DIODE $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	$I_F=400\text{A}$	$T_j=25^\circ\text{C}$		2.1	2.2	V
			$T_j=125^\circ\text{C}$		2.2	2.3	
Q_r	Diode Reverse Recovery Charge	$I_F=400\text{A},$ $V_R=600\text{V},$ $di/dt=-4000\text{A}/\mu\text{s},$ $V_{GE}=-15\text{V}$	$T_j=25^\circ\text{C}$		40		μC
			$T_j=125^\circ\text{C}$		48		
I_{RM}	Diode Peak Reverse Recovery Current		$T_j=25^\circ\text{C}$		320		A
			$T_j=125^\circ\text{C}$		400		
E_{rec}	Reverse Recovery Energy		$T_j=25^\circ\text{C}$		12		mJ
			$T_j=125^\circ\text{C}$		20		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (IGBT Part, per Module)		0.05	K/W
$R_{\theta JC}$	Junction-to-Case (DIODE Part, per Module)		0.09	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.035		K/W
Weight	Weight of Module	300		g



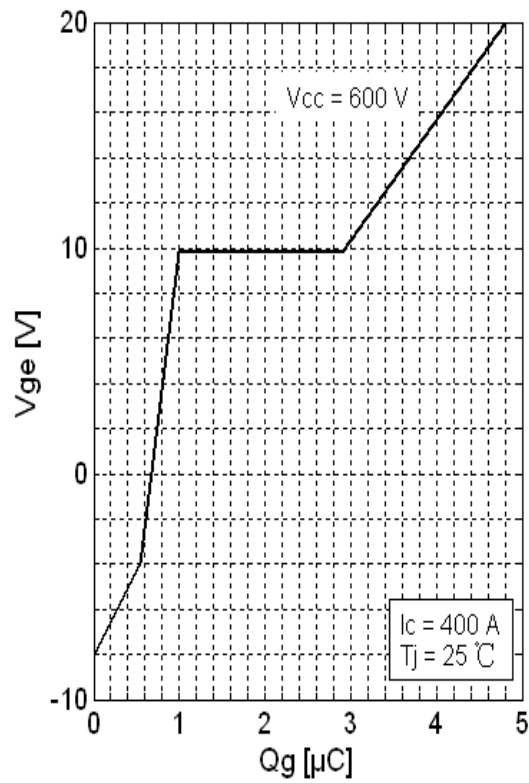


Fig 5. Gate Charge Characteristics.

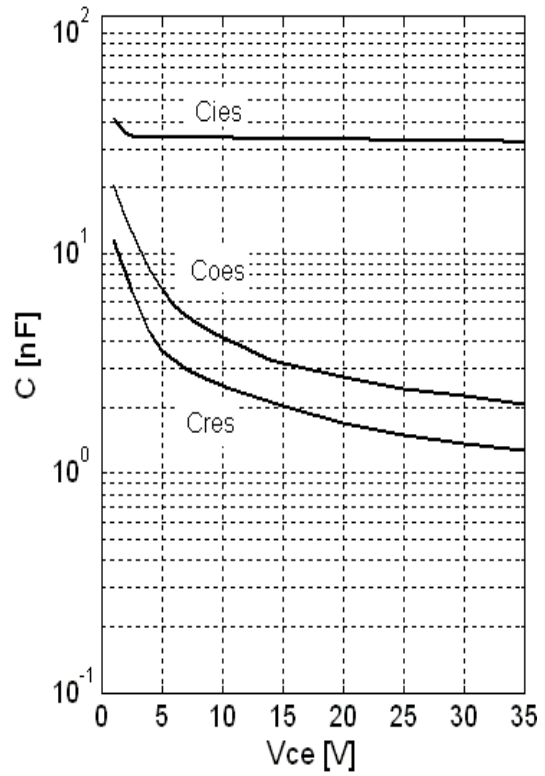


Fig 6. Typical Capacitance vs Collector-Emitter Voltage

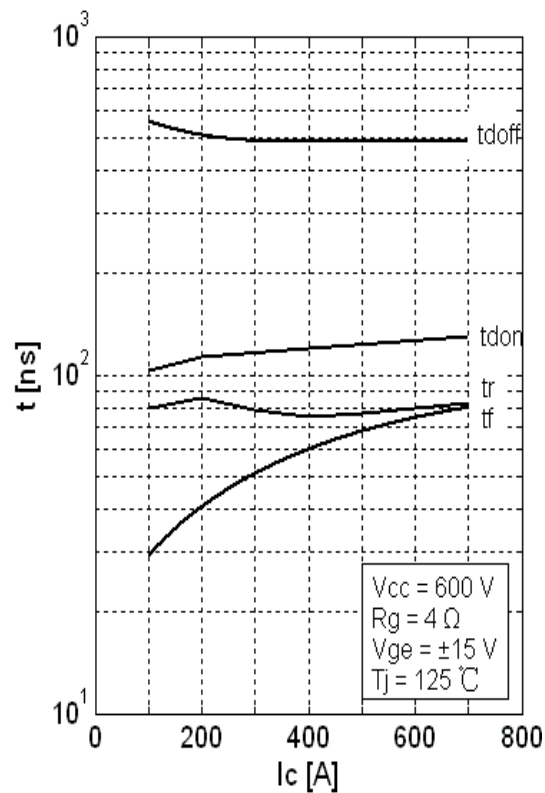


Fig 7. Typical Switching Times vs I_c

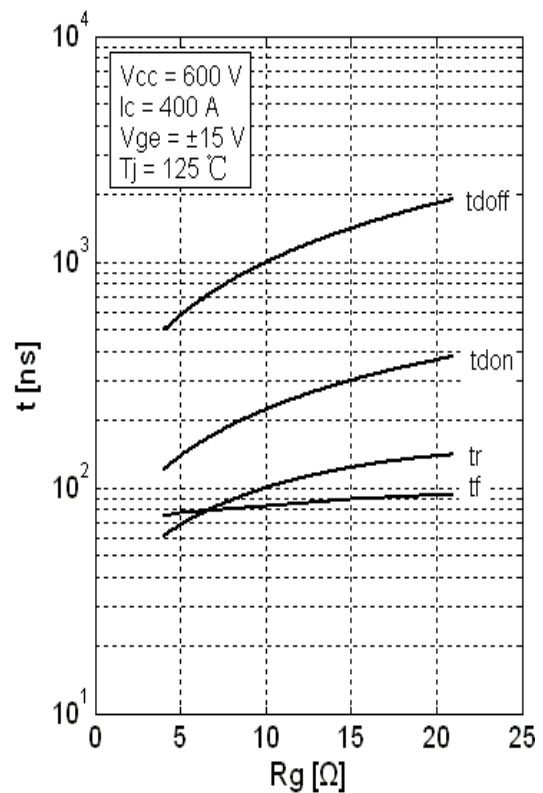


Fig 8. Typical Switching Times vs Gate Resistance R_g

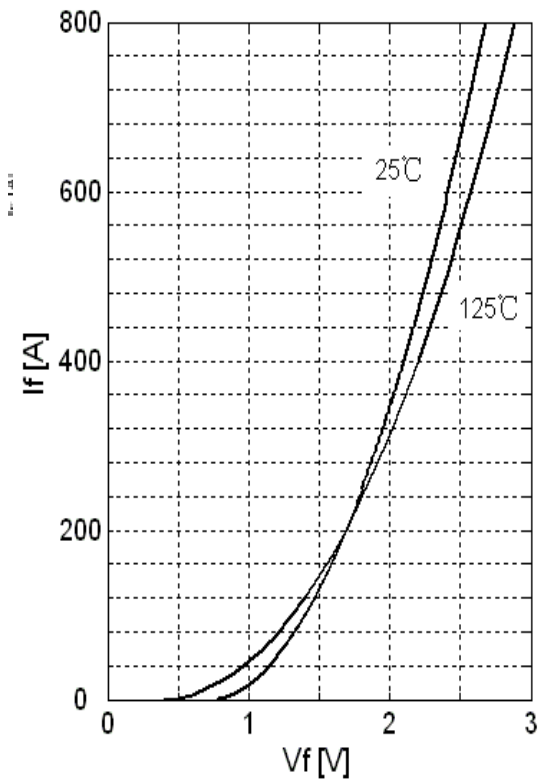


Fig 9. Typical Forward Characteristics (diode)

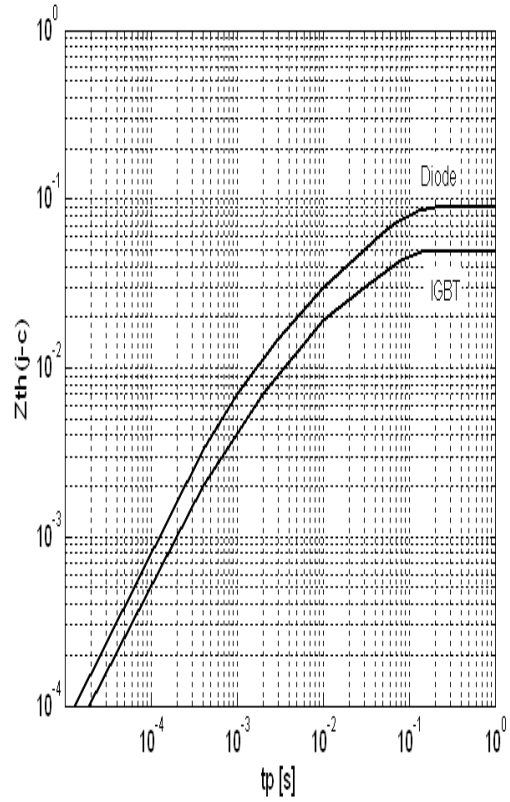
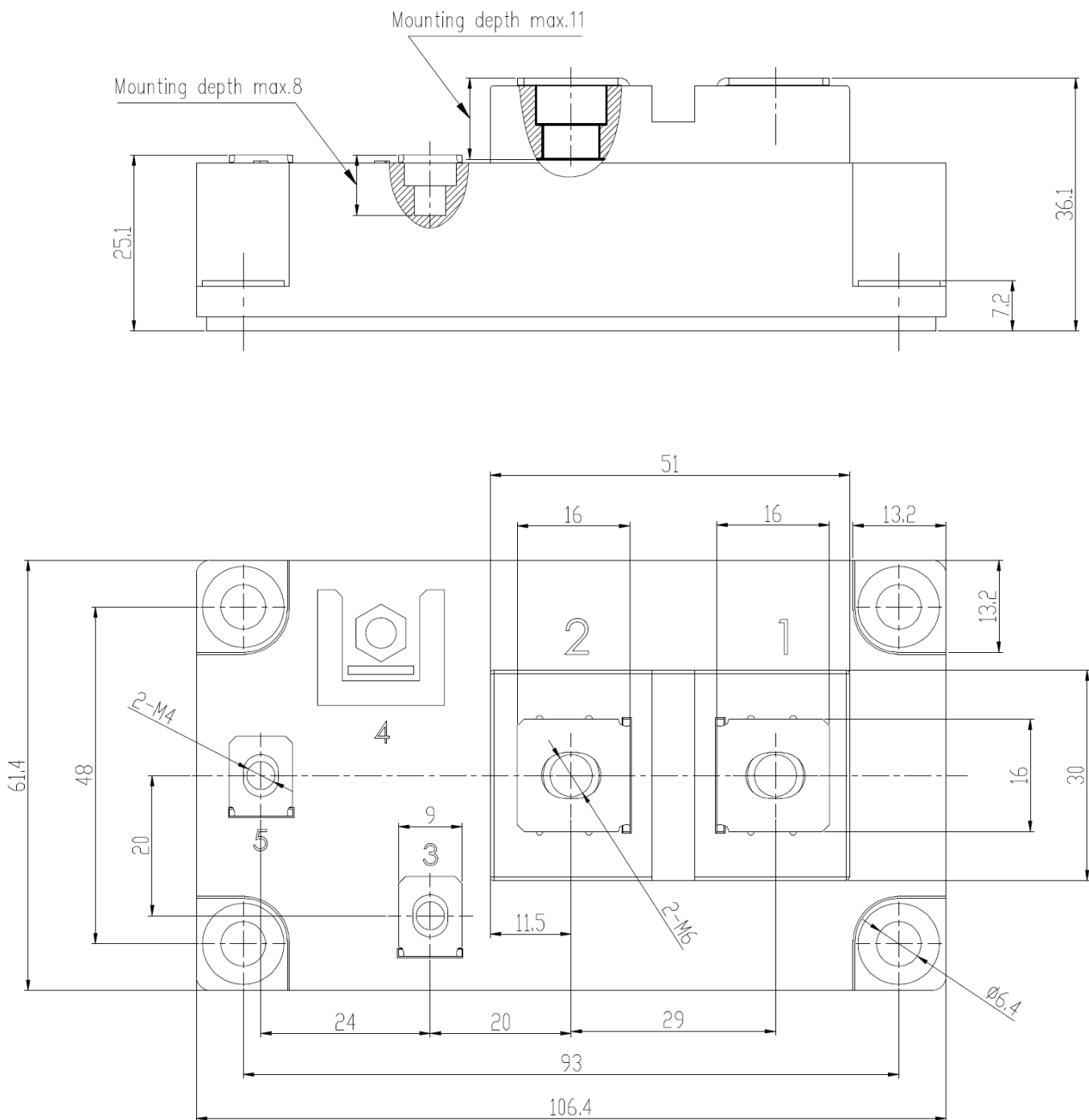


Fig 10. Transient thermal impedance

Package Dimension

Dimensions in Millimeters



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